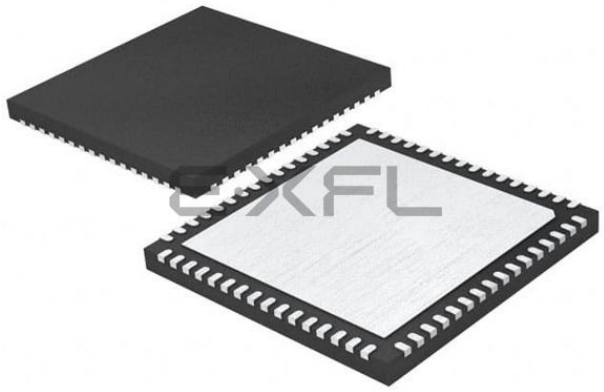
Microchip Technology - DSPIC33FJ128MC706A-E/MR Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, QEI, WDT
Number of I/O	53
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 16x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj128mc706a-e-mr

Pin Diagrams (Continued)

100-Pin TQFP

■ = Pins are up to 5V tolerant

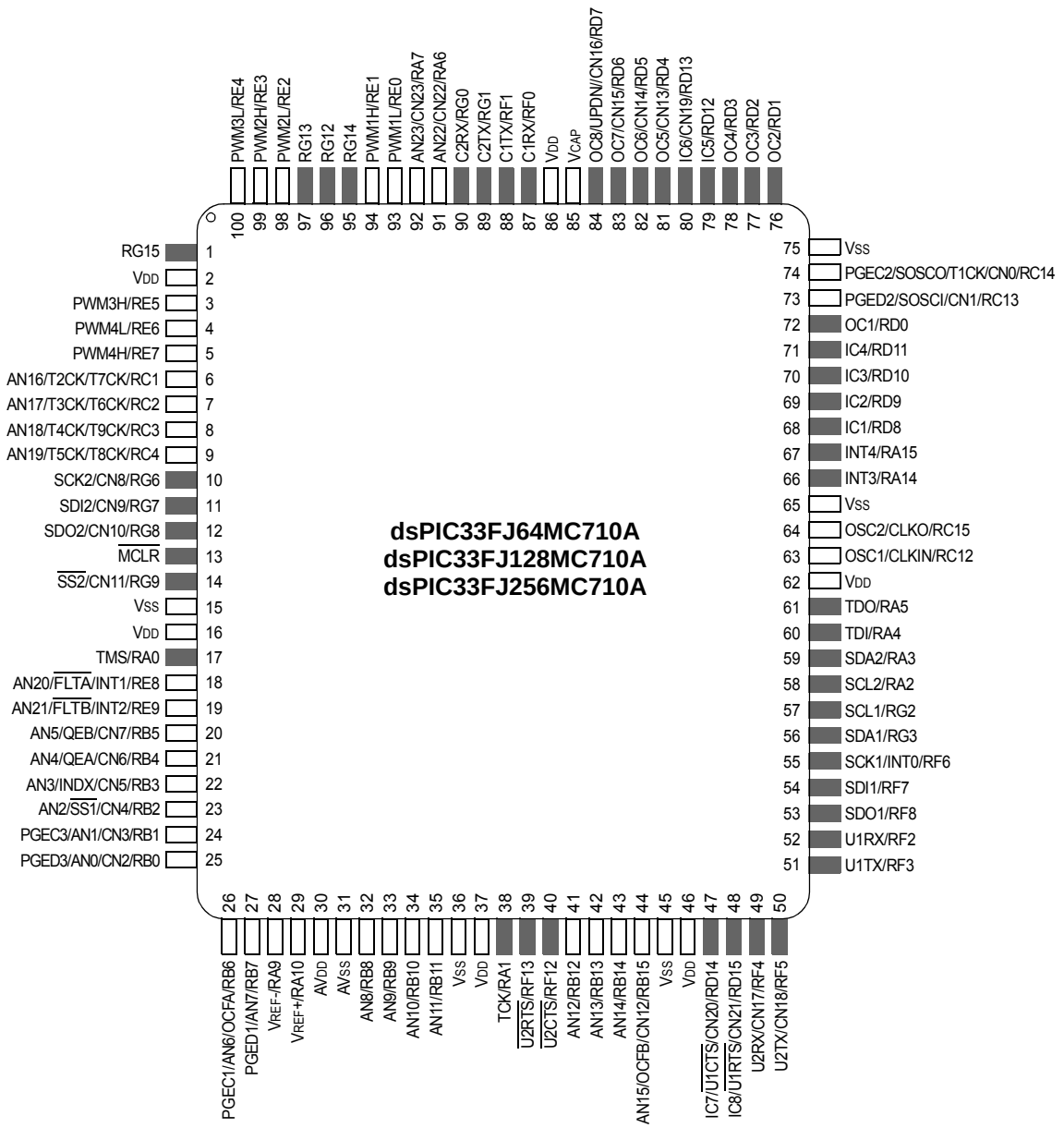


TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Type	Buffer Type	Description
RA0-RA7 RA9-RA10 RA12-RA15	I/O I/O I/O	ST ST ST	PORTA is a bidirectional I/O port.
RB0-RB15	I/O	ST	PORTB is a bidirectional I/O port.
RC1-RC4 RC12-RC15	I/O I/O	ST ST	PORTC is a bidirectional I/O port.
RD0-RD15	I/O	ST	PORTD is a bidirectional I/O port.
RE0-RE9	I/O	ST	PORTE is a bidirectional I/O port.
RF0-RF8 RF12-RF13	I/O	ST	PORTF is a bidirectional I/O port.
RG0-RG3 RG6-RG9 RG12-RG15	I/O I/O I/O	ST ST ST	PORTG is a bidirectional I/O port.
SCK1 SDI1 SDO1 SS1 SCK2 SDI2 SDO2 SS2	I/O I O I/O I/O I O I/O	ST ST — ST ST ST — ST	Synchronous serial clock input/output for SPI1. SPI1 data in. SPI1 data out. SPI1 slave synchronization or frame pulse I/O. Synchronous serial clock input/output for SPI2. SPI2 data in. SPI2 data out. SPI2 slave synchronization or frame pulse I/O.
SCL1 SDA1 SCL2 SDA2	I/O I/O I/O I/O	ST ST ST ST	Synchronous serial clock input/output for I2C1. Synchronous serial data input/output for I2C1. Synchronous serial clock input/output for I2C2. Synchronous serial data input/output for I2C2.
SOSCI SOSCO	I O	ST/CMOS —	32.768 kHz low-power oscillator crystal input; CMOS otherwise. 32.768 kHz low-power oscillator crystal output.
TMS TCK TDI TDO	I I I O	ST ST ST —	JTAG Test mode select pin. JTAG test clock input pin. JTAG test data input pin. JTAG test data output pin.
T1CK T2CK T3CK T4CK T5CK T6CK T7CK T8CK T9CK	I I I I I I I I I	ST ST ST ST ST ST ST ST ST	Timer1 external clock input. Timer2 external clock input. Timer3 external clock input. Timer4 external clock input. Timer5 external clock input. Timer6 external clock input. Timer7 external clock input. Timer8 external clock input. Timer9 external clock input.
U1CTS U1RTS U1RX U1TX U2CTS U2RTS U2RX U2TX	I O I O I O I O	ST — ST — ST — ST —	UART1 clear to send. UART1 ready to send. UART1 receive. UART1 transmit. UART2 clear to send. UART2 ready to send. UART2 receive. UART2 transmit.
VDD	P	—	Positive supply for peripheral logic and I/O pins.
VCAP	P	—	CPU logic filter capacitor connection.

Legend: CMOS = CMOS compatible input or output Analog = Analog input P = Power
ST = Schmitt Trigger input with CMOS levels O = Output I = Input

NOTES:

TABLE 4-10: QEI REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset State
QEI1CON	01E0	CNTERR	—	QEISIDL	INDX	UPDN	QEIM<2:0>			SWPAB	PCDOUT	TQGATE	TQCKPS<1:0>		POSRES	TQCS	UPDN_SRC	0000 0000 0000 0000
DFLT1CON	01E2	—	—	—	—	—	IMV<1:0>		CEID	QEOUT	QECK<2:0>			—	—	—	—	0000 0000 0000 0000
POS1CNT	01E4	Position Counter<15:0>																0000 0000 0000 0000
MAX1CNT	01E6	Maximum Count<15:0>																1111 1111 1111 1111

Legend: u = uninitialized bit, — = unimplemented, read as '0'

TABLE 4-11: I2C1 REGISTER MAP

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
I2C1RCV	0200	—	—	—	—	—	—	—	—	I2C1 Receive Register								0000
I2C1TRN	0202	—	—	—	—	—	—	—	—	I2C1 Transmit Register								00FF
I2C1BRG	0204	—	—	—	—	—	—	—	Baud Rate Generator Register									0000
I2C1CON	0206	I2CEN	—	I2CSIDL	SCLREL	IPMIEN	A10M	DISSLW	SMEN	GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	1000
I2C1STAT	0208	ACKSTAT	TRSTAT	—	—	—	BCL	GCSTAT	ADD10	IWCOL	I2COV	D_A	P	S	R_W	RBF	TBF	0000
I2C1ADD	020A	—	—	—	—	—	—	I2C1 Address Register										0000
I2C1MSK	020C	—	—	—	—	—	—	I2C1 Address Mask Register										0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-12: I2C2 REGISTER MAP

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
I2C2RCV	0210	—	—	—	—	—	—	—	—	I2C2 Receive Register								0000
I2C2TRN	0212	—	—	—	—	—	—	—	—	I2C2 Transmit Register								00FF
I2C2BRG	0214	—	—	—	—	—	—	—	Baud Rate Generator Register									0000
I2C2CON	0216	I2CEN	—	I2CSIDL	SCLREL	IPMIEN	A10M	DISSLW	SMEN	GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	1000
I2C2STAT	0218	ACKSTAT	TRSTAT	—	—	—	BCL	GCSTAT	ADD10	IWCOL	I2COV	D_A	P	S	R_W	RBF	TBF	0000
I2C2ADD	021A	—	—	—	—	—	—	I2C2 Address Register										0000
I2C2MSK	021C	—	—	—	—	—	—	I2C2 Address Mask Register										0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

6.2.1 POR AND LONG OSCILLATOR START-UP TIMES

The oscillator start-up circuitry and its associated delay timers are not linked to the device Reset delays that occur at power-up. Some crystal circuits (especially low-frequency crystals) have a relatively long start-up time. Therefore, one or more of the following conditions is possible after SYSRST is released:

- The oscillator circuit has not begun to oscillate.
- The Oscillator Start-up Timer has not expired (if a crystal oscillator is used).
- The PLL has not achieved a lock (if PLL is used).

The device will not begin to execute code until a valid clock source has been released to the system. Therefore, the oscillator and PLL start-up delays must be considered when the Reset delay time must be known.

6.2.2 FAIL-SAFE CLOCK MONITOR (FSCM) AND DEVICE RESETS

If the FSCM is enabled, it begins to monitor the system clock source when SYSRST is released. If a valid clock source is not available at this time, the device automatically switches to the FRC oscillator and the user can switch to the desired crystal oscillator in the Trap Service Routine.

6.2.2.1 FSCM Delay for Crystal and PLL Clock Sources

When the system clock source is provided by a crystal oscillator and/or the PLL, a small delay, TFSCM, is automatically inserted after the POR and PWRT delay times. The FSCM does not begin to monitor the system clock source until this delay expires. The FSCM delay time is nominally 500 μs and provides additional time for the oscillator and/or PLL to stabilize. In most cases, the FSCM delay prevents an oscillator failure trap at a device Reset when the PWRT is disabled.

6.3 Special Function Register Reset States

Most of the Special Function Registers (SFRs) associated with the CPU and peripherals are reset to a particular value at a device Reset. The SFRs are grouped by their peripheral or CPU function and their Reset values are specified in each section of this manual.

The Reset value for each SFR does not depend on the type of Reset, with the exception of two registers. The Reset value for the Reset Control register, RCON, depends on the type of device Reset. The Reset value for the Oscillator Control register, OSCCON, depends on the type of Reset and the programmed values of the oscillator Configuration bits in the FOSC Configuration register.

REGISTER 7-27: IPC12: INTERRUPT PRIORITY CONTROL REGISTER 12

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	T8IP<2:0>			—	MI2C2IP<2:0>		
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	SI2C2IP<2:0>			—	T7IP<2:0>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **T8IP<2:0>:** Timer8 Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as '0'

bit 10-8 **MI2C2IP<2:0>:** I2C2 Master Events Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 7 **Unimplemented:** Read as '0'

bit 6-4 **SI2C2IP<2:0>:** I2C2 Slave Events Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as '0'

bit 2-0 **T7IP<2:0>:** Timer7 Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

9.1 CPU Clocking System

There are seven system clock options provided by the dsPIC33FJXXXMCX06A/X08A/X10A:

- FRC Oscillator
- FRC Oscillator with PLL
- Primary (XT, HS or EC) Oscillator
- Primary Oscillator with PLL
- Secondary (LP) Oscillator
- LPRC Oscillator
- FRC Oscillator with Postscaler

9.1.1 SYSTEM CLOCK SOURCES

The FRC (Fast RC) internal oscillator runs at a nominal frequency of 7.37 MHz. The user software can tune the FRC frequency. User software can optionally specify a factor (ranging from 1:2 to 1:256) by which the FRC clock frequency is divided. This factor is selected using the FRCDIV<2:0> bits (CLKDIV<10:8>).

The primary oscillator can use one of the following as its clock source:

1. XT (Crystal): Crystals and ceramic resonators in the range of 3 MHz to 10 MHz. The crystal is connected to the OSC1 and OSC2 pins.
2. HS (High-Speed Crystal): Crystals in the range of 10 MHz to 40 MHz. The crystal is connected to the OSC1 and OSC2 pins.
3. EC (External Clock): External clock signal is directly applied to the OSC1 pin.

The secondary (LP) oscillator is designed for low power and uses a 32.768 kHz crystal or ceramic resonator. The LP oscillator uses the SOSCI and SOSCO pins.

The LPRC (Low-Power RC) internal oscIllator runs at a nominal frequency of 32.768 kHz. It is also used as a reference clock by the Watchdog Timer (WDT) and Fail-Safe Clock Monitor (FSCM).

The clock signals generated by the FRC and primary oscillators can be optionally applied to an on-chip Phase-Locked Loop (PLL) to provide a wide range of output frequencies for device operation. PLL configuration is described in **Section 9.1.3 "PLL Configuration"**.

The FRC frequency depends on the FRC accuracy (see Table 26-19) and the value of the FRC Oscillator Tuning register (see Register 9-4).

9.1.2 SYSTEM CLOCK SELECTION

The oscillator source that is used at a device Power-on Reset event is selected using Configuration bit settings. The oscillator Configuration bit settings are located in the Configuration registers in the program memory. (Refer to **Section 23.1 "Configuration Bits"** for further details.) The Initial Oscillator Selection Configuration bits, FNOSC<2:0> (FOSCSEL<2:0>), and the Primary Oscillator Mode Select Configuration bits, POSCMD<1:0> (FOSC<1:0>), select the oscillator source that is used at a Power-on Reset. The FRC primary oscillator is the default (unprogrammed) selection.

The Configuration bits allow users to choose between twelve different clock modes, shown in Table 9-1.

The output of the oscillator (or the output of the PLL if a PLL mode has been selected), FOSC, is divided by 2 to generate the device instruction clock (FCY) and the peripheral clock time base (FP). FCY defines the operating speed of the device and speeds up to 40 MHz are supported by the dsPIC33FJXXXMCX06A/X08A/X10A architecture.

Instruction execution speed or device operating frequency, FCY, is given by the following equation:

EQUATION 9-1: DEVICE OPERATING FREQUENCY

$$FCY = \frac{FOSC}{2}$$

9.1.3 PLL CONFIGURATION

The primary oscillator and internal FRC oscillator can optionally use an on-chip PLL to obtain higher speeds of operation. The PLL provides a significant amount of flexibility in selecting the device operating speed. A block diagram of the PLL is shown in Figure 9-2.

The output of the primary oscillator or FRC, denoted as 'FIN', is divided down by a prescale factor (N1) of 2, 3, ... or 33 before being provided to the PLL's Voltage Controlled Oscillator (VCO). The input to the VCO must be selected to be in the range of 0.8 MHz to 8 MHz. Since the minimum prescale factor is 2, this implies that FIN must be chosen to be in the range of 1.6 MHz to 16 MHz. The prescale factor, 'N1', is selected using the PLLPRE<4:0> bits (CLKDIV<4:0>).

The PLL feedback divisor, selected using the PLLDIV<8:0> bits (PLLFBD<8:0>), provides a factor, 'M', by which the input to the VCO is multiplied. This factor must be selected such that the resulting VCO output frequency is in the range of 100 MHz to 200 MHz.

The VCO output is further divided by a postscale factor, 'N2'. This factor is selected using the PLLPOST<1:0> bits (CLKDIV<7:6>). 'N2' can be either 2, 4 or 8, and must be selected such that the PLL output frequency (FOSC) is in the range of 12.5 MHz to 80 MHz, which generates device operating speeds of 6.25-40 MIPS.

For a primary oscillator or FRC oscillator output, 'FIN', the PLL output, 'FOSC', is given by the following equation:

EQUATION 9-2: FOSC CALCULATION

$$FOSC = FIN \cdot \left(\frac{M}{N1 \cdot N2}\right)$$

15.1 Output Compare Modes

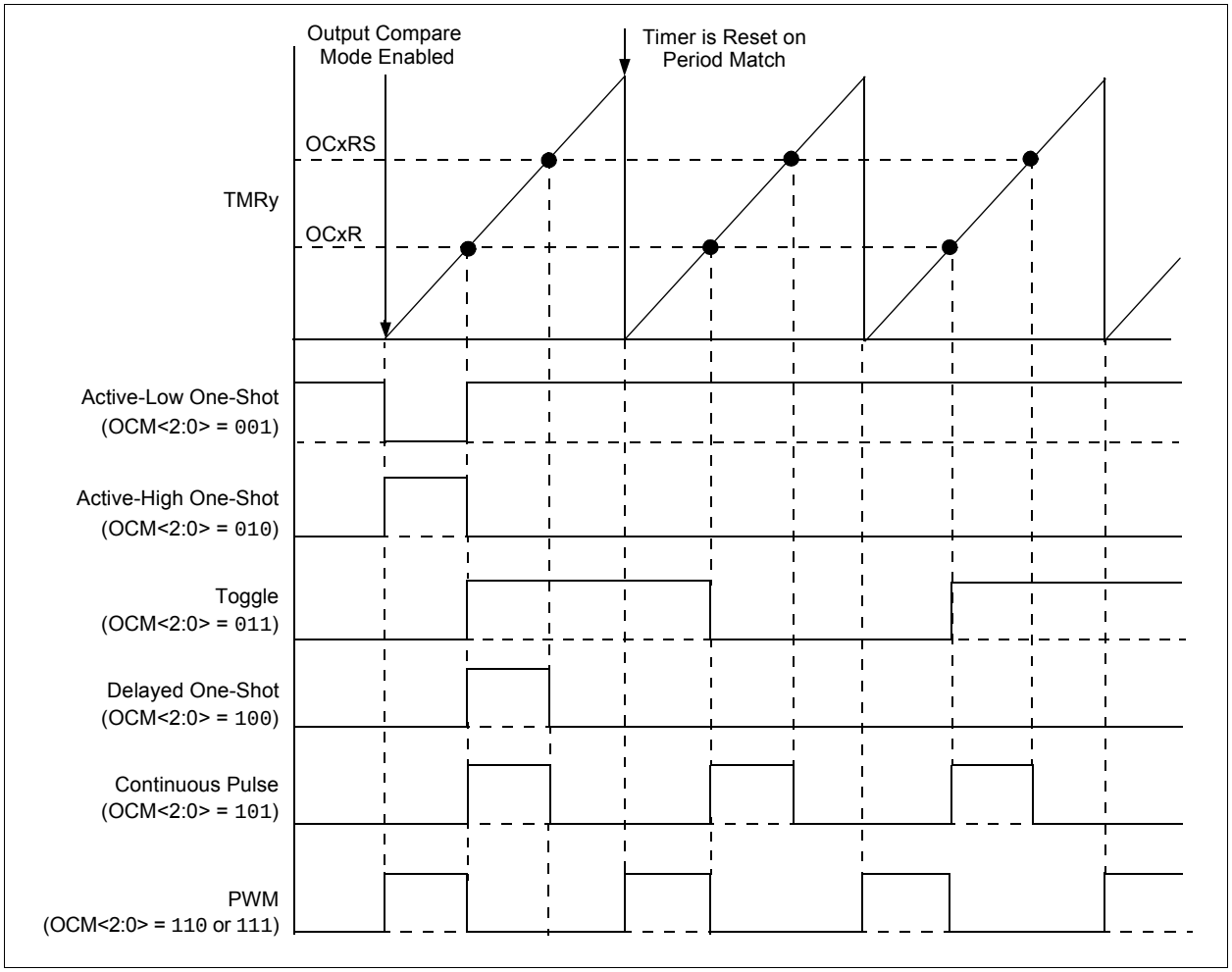
Configure the Output Compare modes by setting the appropriate Output Compare Mode bits (OCM<2:0>) in the Output Compare Control register (OCxCON<2:0>). Table 15-1 lists the different bit settings for the Output Compare modes. Figure 15-2 illustrates the output compare operation for various modes. The user application must disable the associated timer when writing to the Output Compare Control registers to avoid malfunctions.

Note:	See **Section 13. "Output Compare"** (DS70209) in the *"dsPIC33F/PIC24H Family Reference Manual"* for OCxR and OCxRS register restrictions.

TABLE 15-1: OUTPUT COMPARE MODES

OCM<2:0>	Mode	OCx Pin Initial State	OCx Interrupt Generation
000	Module Disabled	Controlled by GPIO register	—
001	Active-Low One-Shot	0	OCx rising edge
010	Active-High One-Shot	1	OCx falling edge
011	Toggle	Current output is maintained	OCx rising and falling edge
100	Delayed One-Shot	0	OCx falling edge
101	Continuous Pulse	0	OCx falling edge
110	PWM without Fault Protection	'0' if OCxR is zero, '1' if OCxR is non-zero	No interrupt
111	PWM with Fault Protection	'0' if OCxR is zero, '1' if OCxR is non-zero	OCFA falling edge for OC1 to OC4

FIGURE 15-2: OUTPUT COMPARE OPERATION



REGISTER 19-1: I2CxCON: I2Cx CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-1, HC	R/W-0	R/W-0	R/W-0	R/W-0
I2CEN	—	I2CSIDL	SCLREL	IPMIEN	A10M	DISSLW	SMEN
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0, HC	R/W-0, HC	R/W-0, HC	R/W-0, HC	R/W-0, HC
GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN
bit 7							bit 0

Legend:	U = Unimplemented bit, read as '0'		
R = Readable bit	W = Writable bit	HS = Hardware Settable bit	HC = Hardware Clearable bit
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **I2CEN:** I2Cx Enable bit
1 = Enables the I2Cx module and configures the SDAx and SCLx pins as serial port pins
0 = Disables the I2Cx module. All I^2C™ pins are controlled by port functions.

bit 14 **Unimplemented:** Read as '0'

bit 13 **I2CSIDL:** Stop in Idle Mode bit
1 = Discontinue module operation when device enters an Idle mode
0 = Continue module operation in Idle mode

bit 12 **SCLREL:** SCLx Release Control bit (when operating as I^2C slave)
1 = Release SCLx clock
0 = Hold SCLx clock low (clock stretch)
If STREN = 1:
Bit is R/W (i.e., software may write '0' to initiate stretch and write '1' to release clock). Hardware clear at beginning of slave transmission. Hardware clear at end of slave reception.
If STREN = 0:
Bit is R/S (i.e., software may only write '1' to release clock). Hardware clear at beginning of slave transmission.

bit 11 **IPMIEN:** Intelligent Peripheral Management Interface (IPMI) Enable bit
1 = IPMI mode is enabled; all addresses Acknowledged
0 = IPMI mode disabled

bit 10 **A10M:** 10-Bit Slave Address bit
1 = I2CxADD is a 10-bit slave address
0 = I2CxADD is a 7-bit slave address

bit 9 **DISSLW:** Disable Slew Rate Control bit
1 = Slew rate control disabled
0 = Slew rate control enabled

bit 8 **SMEN:** SMBus Input Levels bit
1 = Enable I/O pin thresholds compliant with SMBus specification
0 = Disable SMBus input thresholds

bit 7 **GCEN:** General Call Enable bit (when operating as I^2C slave)
1 = Enable interrupt when a general call address is received in the I2CxRSR (module is enabled for reception)
0 = General call address disabled

bit 6 **STREN:** SCLx Clock Stretch Enable bit (when operating as I^2C slave)
Used in conjunction with the SCLREL bit.
1 = Enable software or receive clock stretching
0 = Disable software or receive clock stretching

REGISTER 21-4: CiFCTRL: ECAN™ FIFO CONTROL REGISTER

R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0	U-0
DMABS<2:0>			—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	FSA<4:0>				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **DMABS<2:0>:** DMA Buffer Size bits
111 = Reserved
110 = 32 buffers in DMA RAM
101 = 24 buffers in DMA RAM
100 = 16 buffers in DMA RAM
011 = 12 buffers in DMA RAM
010 = 8 buffers in DMA RAM
001 = 6 buffers in DMA RAM
000 = 4 buffers in DMA RAM

bit 12-5 **Unimplemented:** Read as ‘0’

bit 4-0 **FSA<4:0>:** FIFO Area Starts with Buffer bits
11111 = RB31 buffer
11110 = RB30 buffer
•
•
•
00001 = TRB1 buffer
00000 = TRB0 buffer

REGISTER 21-26: CiTRmnCON: ECAN™ TX/RX BUFFER mn CONTROL REGISTER (m = 0,2,4,6; n = 1,3,5,7)

R/W-0	R-0	R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0
TXENn	TXABTn	TXLARBn	TXERRn	TXREQn	RTRENn	TXnPRI<1:0>	
bit 15							bit 8

R/W-0	R-0	R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0
TXENm	TXABTm(1)	TXLARBm(1)	TXERRm(1)	TXREQm	RTRENm	TXmPRI<1:0>	
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **See Definition for Bits 7-0, Controls Buffer n**

bit 7 **TXENm:** TX/RX Buffer Selection bit
1 = Buffer TRBn is a transmit buffer
0 = Buffer TRBn is a receive buffer

bit 6 **TXABTm:** Message Aborted bit(1)
1 = Message was aborted
0 = Message completed transmission successfully

bit 5 **TXLARBm:** Message Lost Arbitration bit(1)
1 = Message lost arbitration while being sent
0 = Message did not lose arbitration while being sent

bit 4 **TXERRm:** Error Detected During Transmission bit(1)
1 = A bus error occurred while the message was being sent
0 = A bus error did not occur while the message was being sent

bit 3 **TXREQm:** Message Send Request bit
Setting this bit to '1' requests sending a message. The bit will automatically clear when the message is successfully sent. Clearing the bit to '0' while set will request a message abort.

bit 2 **RTRENm:** Auto-Remote Transmit Enable bit
1 = When a remote transmit is received, TXREQ will be set
0 = When a remote transmit is received, TXREQ will be unaffected

bit 1-0 **TXmPRI<1:0>:** Message Transmission Priority bits
11 = Highest message priority
10 = High intermediate message priority
01 = Low intermediate message priority
00 = Lowest message priority

Note 1: This bit is cleared when TXREQ is set.

REGISTER 21-29: CiTRBnDLC: ECAN™ BUFFER n DATA LENGTH CONTROL (n = 0, 1, ..., 31)

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
EID5	EID4	EID3	EID2	EID1	EID0	RTR	RB1
bit 15							bit 8

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	RB0	DLC3	DLC2	DLC1	DLC0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-10 **EID<5:0>:** Extended Identifier bits

bit 9 **RTR:** Remote Transmission Request bit
1 = Message will request remote transmission
0 = Normal message

bit 8 **RB1:** Reserved Bit 1
User must set this bit to '0' per CAN protocol.

bit 7-5 **Unimplemented:** Read as '0'

bit 4 **RB0:** Reserved Bit 0
User must set this bit to '0' per CAN protocol.

bit 3-0 **DLC<3:0>:** Data Length Code bits

REGISTER 21-30: CiTRBnDm: ECAN™ BUFFER n DATA FIELD BYTE m (n = 0, 1, ..., 31; m = 0, 1, ..., 7)(1)

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
TRBnDm<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 **TRnDm<7:0>:** Data Field Buffer 'n' Byte 'm' bits

Note 1: The Most Significant Byte contains byte (m + 1) of the buffer.

TABLE 26-7: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD})

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.(3)	**Typical(2)**	**Max**	**Units**	**Conditions**		
Power-Down Current (I_{PD})(1)						
DC60d	50	200	µA	-40°C	3.3V	Base Power-Down Current(3)
DC60a	50	200	µA	+25°C		
DC60b	200	500	µA	+85°C		
DC60c	600	1000	µA	+125°C		
DC61d	8	13	µA	-40°C	3.3V	Watchdog Timer Current: ΔI_{WDT}(3)
DC61a	10	15	µA	+25°C		
DC61b	12	20	µA	+85°C		
DC61c	13	25	µA	+125°C		

Note 1: I_{PD} (Sleep) current is measured as follows:

- CPU core is off, oscillator is configured in EC mode and external clock active, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration word
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{MCLR}$ = V_{DD}, WDT and FSCM are disabled, all peripheral modules except the ADC are disabled (PMDx bits are all '1's). The following ADC settings are enabled for each ADC module (ADCx) prior to executing the PWRSAV instruction: ADON = 1, VCFG = 1, AD12B = 1 and ADxMD = 0.
- VREGS bit (RCON<8>) = 0 (i.e., core regulator is set to stand-by while the device is in Sleep mode)
- RTCC is disabled.
- JTAG is disabled

2: Data in the "Typ" column is at 3.3V, +25ºC unless otherwise stated.

3: The Watchdog Timer Current is the additional current consumed when the WDT module is enabled. This current should be added to the base I_{PD} current.

4: These currents are measured on the device containing the most memory in this family.

5: These parameters are characterized, but are not tested in manufacturing.

FIGURE 26-13: TIMERQ (QEI MODULE) EXTERNAL CLOCK TIMING CHARACTERISTICS

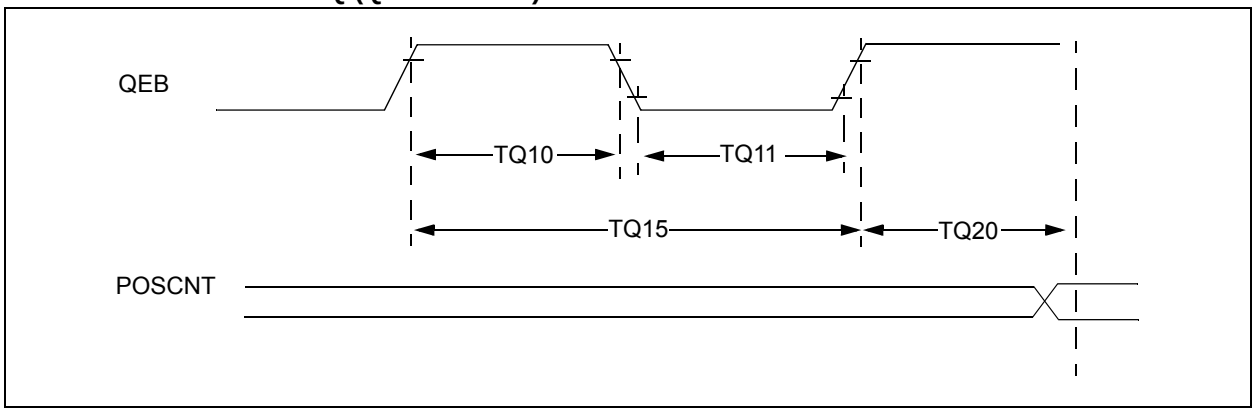


TABLE 26-31: QEI MODULE EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**		**Min**	**Typ**	**Max**	**Units**	**Conditions**
TQ10	TtQH	TQCK High Time	Synchronous, with prescaler	TCY + 20	—	—	ns	Must also meet parameter TQ15
TQ11	TtQL	TQCK Low Time	Synchronous, with prescaler	TCY + 20	—	—	ns	Must also meet parameter TQ15
TQ15	TtQP	TQCP Input Period	Synchronous, with prescaler	2 * TCY + 40	—	—	ns	—
TQ20	TCKEXTMRL	Delay from External TxCK Clock Edge to Timer Increment		0.5 TCY	—	1.5 TCY	—	—

Note 1: These parameters are characterized but not tested in manufacturing.

TABLE 26-33: SPIx MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP10	TscP	Maximum SCK Frequency	—	—	15	MHz	See **Note 3**
SP20	TscF	SCKx Output Fall Time	—	—	—	ns	See parameter DO32 and **Note 4**
SP21	TscR	SCKx Output Rise Time	—	—	—	ns	See parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	—
SP36	TdiV2scH, TdiV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	—

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typ” column is at 3.3V, 25°C unless otherwise stated.

3: The minimum clock period for SCKx is 66.7 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

FIGURE 26-24: I2Cx BUS START/STOP BITS TIMING CHARACTERISTICS (SLAVE MODE)

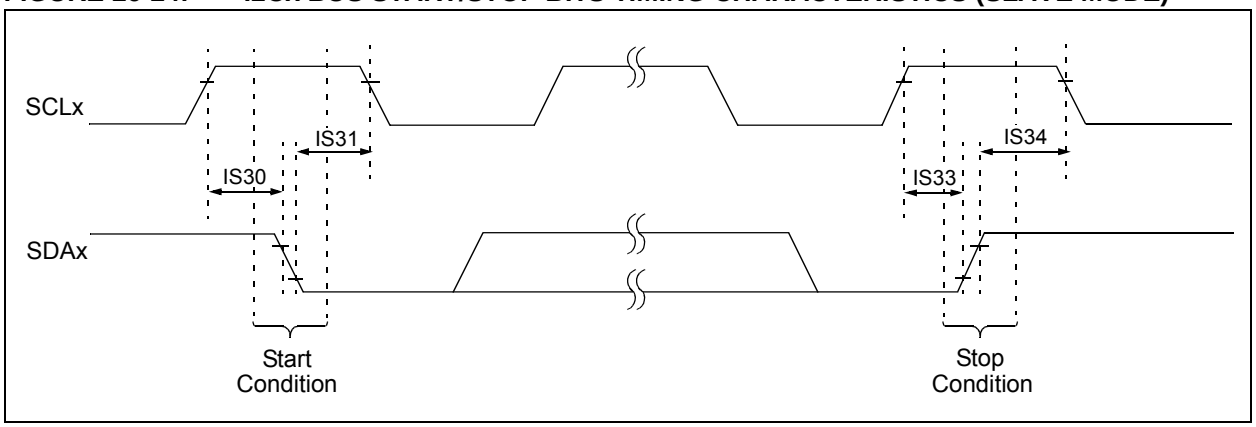


FIGURE 26-25: I2Cx BUS DATA TIMING CHARACTERISTICS (SLAVE MODE)

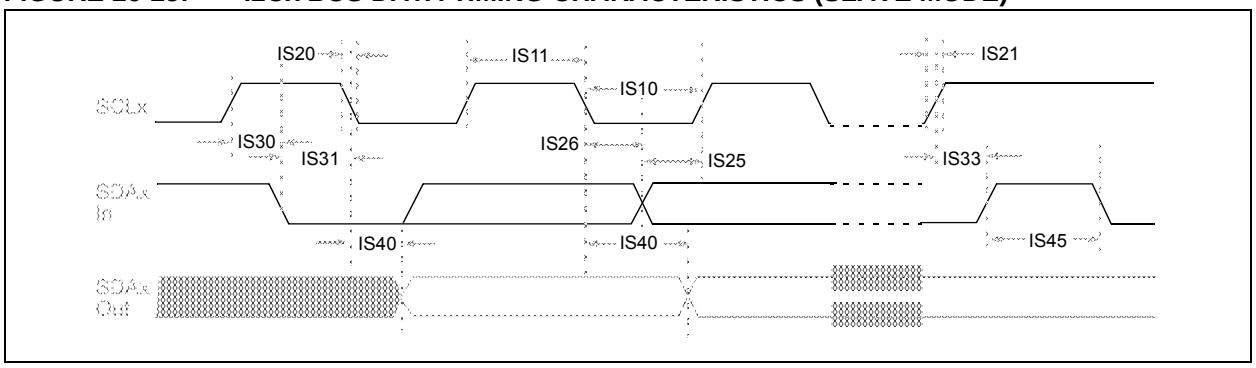


TABLE 26-43: ADC MODULE SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ**	**Max.**	**Units**	**Conditions**
Device Supply							
AD01	AVDD	Module VDD Supply	Greater of VDD – 0.3 or 3.0	—	Lesser of VDD + 0.3 or 3.6	V	—
AD02	AVSS	Module VSS Supply	VSS – 0.3	—	VSS + 0.3	V	—
Reference Inputs							
AD05	VREFH	Reference Voltage High	AVSS + 2.5	—	AVDD	V	—
AD05a			3.0	—	3.6	V	VREFH = AVDD VREFL = AVSS = 0
AD06	VREFL	Reference Voltage Low	AVSS	—	AVDD – 2.5	V	—
AD06a			0	—	0	V	VREFH = AVDD VREFL = AVSS = 0
AD07	VREF	Absolute Reference Voltage	2.5	—	3.6	V	VREF = VREFH - VREFL
AD08	IREF	Current Drain	—	—	10	μA	ADC off
AD08a	IAD	Operating Current	— —	7.0 2.7	9.0 3.2	mA mA	10-bit ADC mode, see **Note 1** 12-bit ADC mode, see **Note 1**
Analog Input							
AD12	VINH	Input Voltage Range VINH	VINL	—	VREFH	V	This voltage reflects Sample and Hold Channels 0, 1, 2 and 3 (CH0-CH3), positive input
AD13	VINL	Input Voltage Range VINL	VREFL	—	AVSS + 1V	V	This voltage reflects Sample and Hold Channels 0, 1, 2 and 3 (CH0-CH3), negative input
AD17	RIN	Recommended Impedance of Analog Voltage Source	— —	— —	200 200	Ω Ω	10-bit ADC 12-bit ADC

Note 1: These parameters are not characterized or tested in manufacturing.

TABLE 27-6: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for High Temperature				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
HDO10	VOL	**Output Low Voltage** I/O Pins: 2x Sink Driver Pins - All pins not defined by 4x or 8x driver pins	—	—	0.4	V	IOL ≤ 1.8 mA, VDD = 3.3V See **Note 1**
		Output Low Voltage I/O Pins: 4x Sink Driver Pins - RA2, RA3, RA9, RA10, RA14, RA15, RB0, RB1, RB11, RF4, RF5, RG2, RG3	—	—	0.4	V	IOL ≤ 3.6 mA, VDD = 3.3V See **Note 1**
		Output Low Voltage I/O Pins: 8x Sink Driver Pins - OSC2, CLKO, RC15	—	—	0.4	V	IOL ≤ 6 mA, VDD = 3.3V See **Note 1**
HDO20	VOH	**Output High Voltage** I/O Pins: 2x Source Driver Pins - All pins not defined by 4x or 8x driver pins	2.4	—	—	V	IOL ≥ -1.8 mA, VDD = 3.3V See **Note 1**
		Output High Voltage I/O Pins: 4x Source Driver Pins - RA2, RA3, RA9, RA10, RA14, RA15, RB0, RB1, RB11, RF4, RF5, RG2, RG3	2.4	—	—	V	IOL ≥ -3 mA, VDD = 3.3V See **Note 1**
		Output High Voltage I/O Pins: 8x Source Driver Pins - OSC2, CLKO, RC15	2.4	—	—	V	IOL ≥ -6 mA, VDD = 3.3V See **Note 1**
HDO20A	VOH1	**Output High Voltage** I/O Pins: 2x Source Driver Pins - All pins not defined by 4x or 8x driver pins	1.5	—	—	V	IOH ≥ -1.9 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -1.85 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -1.4 mA, VDD = 3.3V See **Note 1**
		Output High Voltage 4x Source Driver Pins - RA2, RA3, RA9, RA10, RA14, RA15, RB0, RB1, RB11, RF4, RF5, RG2, RG3	1.5	—	—	V	IOH ≥ -3.9 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -3.7 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -2 mA, VDD = 3.3V See **Note 1**
		Output High Voltage 8x Source Driver Pins - OSC2, CLKO, RC15	1.5	—	—	V	IOH ≥ -7.5 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -6.8 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -3 mA, VDD = 3.3V See **Note 1**

Note 1: Parameters are characterized, but not tested.

TABLE 27-14: ADC MODULE SPECIFICATIONS

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature					
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
Reference Inputs							
HAD08	IREF	Current Drain	— —	250 —	600 50	μA μA	ADC operating, See **Note 1** ADC off, See **Note 1**

Note 1: These parameters are not characterized or tested in manufacturing.

TABLE 27-15: ADC MODULE SPECIFICATIONS (12-BIT MODE)(3)

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature					
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
ADC Accuracy (12-bit Mode) – Measurements with external VREF+/VREF-(1)							
AD23a	GERR	Gain Error	—	5	10	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
AD24a	EOFF	Offset Error	—	2	5	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
ADC Accuracy (12-bit Mode) – Measurements with internal VREF+/VREF-(1)							
AD23a	GERR	Gain Error	2	10	20	LSb	VINL = AVSS = 0V, AVDD = 3.6V
AD24a	EOFF	Offset Error	2	5	10	LSb	VINL = AVSS = 0V, AVDD = 3.6V
Dynamic Performance (12-bit Mode)(2)							
HAD33a	FNYQ	Input Signal Bandwidth	—	—	200	kHz	—

Note 1: These parameters are characterized, but are tested at 20 ksps only.

2: These parameters are characterized by similarity, but are not tested in manufacturing.

3: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.

TABLE 27-16: ADC MODULE SPECIFICATIONS (10-BIT MODE)(3)

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature					
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
ADC Accuracy (12-bit Mode) – Measurements with external VREF+/VREF-(1)							
AD23b	GERR	Gain Error	—	3	6	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
AD24b	EOFF	Offset Error	—	2	5	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
ADC Accuracy (12-bit Mode) – Measurements with internal VREF+/VREF-(1)							
AD23b	GERR	Gain Error	—	7	15	LSb	VINL = AVSS = 0V, AVDD = 3.6V
AD24b	EOFF	Offset Error	—	3	7	LSb	VINL = AVSS = 0V, AVDD = 3.6V
Dynamic Performance (10-bit Mode)(2)							
HAD33b	FNYQ	Input Signal Bandwidth	—	—	400	kHz	—

Note 1: These parameters are characterized, but are tested at 20 ksps only.

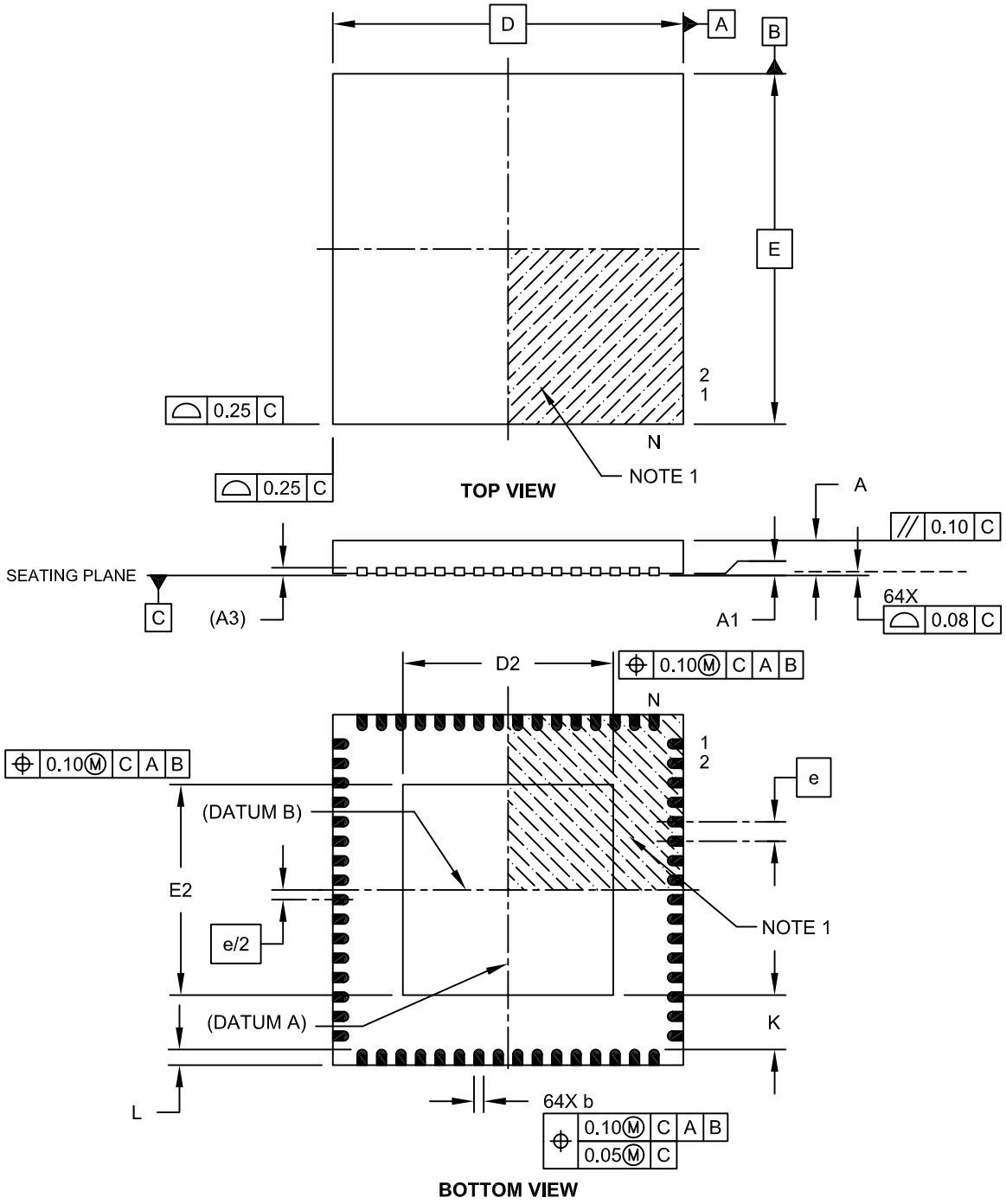
2: These parameters are characterized by similarity, but are not tested in manufacturing.

3: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.

29.2 Package Details

64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body with 5.40 x 5.40 Exposed Pad [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-154A Sheet 1 of 2